

Amendments to the Specification

At page 1, line 2, after the title of invention and before the first paragraph please insert the following subtitle:

Technical Field

At page 1, line 7, before the second paragraph please insert the following subtitle:

Background Art

30

Change(s) applied At page 4, line 29 please replace the last paragraph with: 1) the following Brief
to document, Summary of the Invention subtitle; 2) the amended paragraph; 3) the new Brief
/T.V.R./ Description of the Drawings section with subtitle; and 4) Detailed Description of the
4/19/2011 Invention subtitle.

Brief Summary of the Invention

Therefore, the The object of the present invention is to provide a process for treating one side of silicon wafers in which it is possible to make do without the process steps of the prior art involving protecting or masking the front surfaces or top sides which are not to be treated, yet the process can preferably be carried out in a production line. The object is accomplished through processes for wet-chemical treatment of one side of a silicon wafer using a liquid bath, during which the wafer lays on conveyor means and the entire surface of the underside to be treated is conveyed through or over liquid located in the liquid bath. In a first embodiment, the conveyor means are positioned within the liquid bath and the top side, which is not to be treated, is always positioned above the liquid. In a second embodiment, the level of the liquid being contacted by the underside is maintained above the level of the bath surface not being contacted by the underside. The top side, which is not to be treated, is always positioned above the level of the liquid.